CY74FCT16652T
CY74FCT162652T

16-Bit Registered Transceiver

Features

- **Low power, pin-compatible replacement for ABT functions**
- **FCT-C speed at 5.4 ns**
- **Power-off disable outputs permits live insertion**
- **Edge-rate control circuitry for significantly improved noise characteristics**
- **Typical output skew < 250 ps**
- **ESD > 2000V**
- **TSSOP (19.6-mil pitch) and SSOP (25-mil pitch) packages**
- **Extended commercial range of −40˚C to +85˚C**
- **V_{CC} = 5V ± 10%**

CY74FCT16652T Features:

- **64 mA sink current (Com'l), 32 mA source current (Com'l)**
- **Typical V_{OLP} (ground bounce) <1.0V at V_{CC} = 5V, T_A = 25˚C**

CY74FCT162652TT Features:

- **Balanced output drivers: 24 mA**
- **Reduced system switching noise**
- **Typical V_{OLP} (ground bounce) <0.6V at V_{CC} = 5V, T_A= 25˚C**

Functional Description

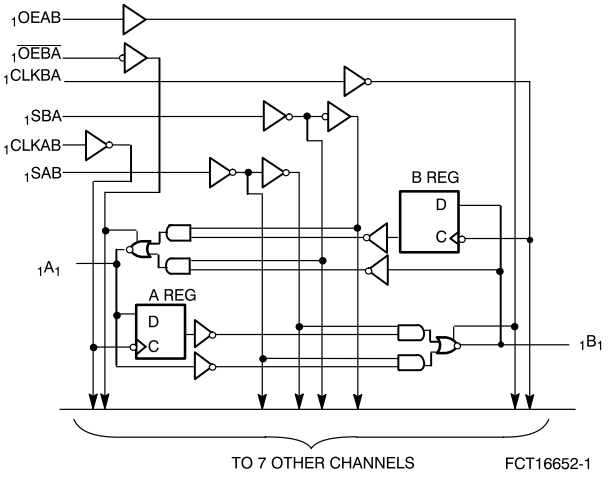
These16-bit, high-speed, low-power, registered transceivers that are organized as two independent 8-bit bus transceivers with three-state D-type registers and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal storage registers. OEAB and $\overline{\text{OEBA}}$ control pins are provided to control the transceiver functions. SAB and SBA control pins are provided to select either real-time or stored data transfer.

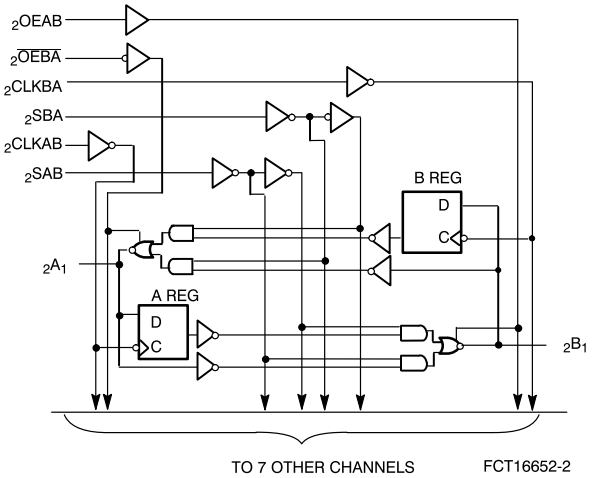
Data on the A or B data bus, or both, can be stored in the internal D flip-flops by LOW-to-HIGH transitions at the appropriate clock pins (CLKAB or CLKBA), regardless of the select or enable control pins. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state. The output buffers are designed with a power-off disable feature that allows live insertion of boards.

The CY74FCT16652T is ideally suited for driving high-capacitance loads and low-impedance backplanes.

The CY74FCT162652T has 24-mA balanced output drivers with current-limiting resistors in the outputs. This reduces the need for external terminating resistors and provides for minimal underhsoot and reduced ground bounce. The CY74FCT162652T is ideal for driving transmission lines.

Logic Block Diagrams

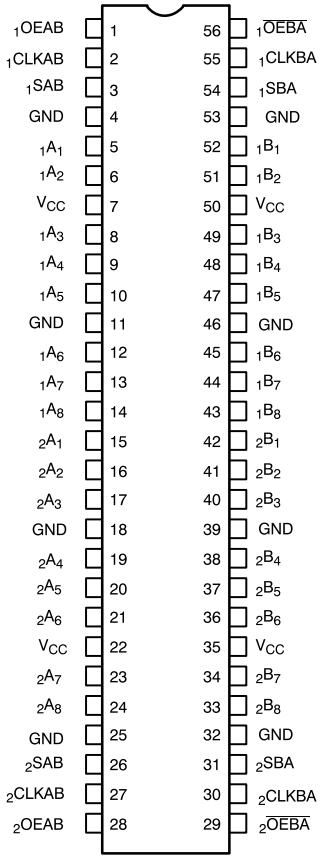




Pin Configuration

SSOP/TSSOP

Top View



FCT16652-3

Pin Description

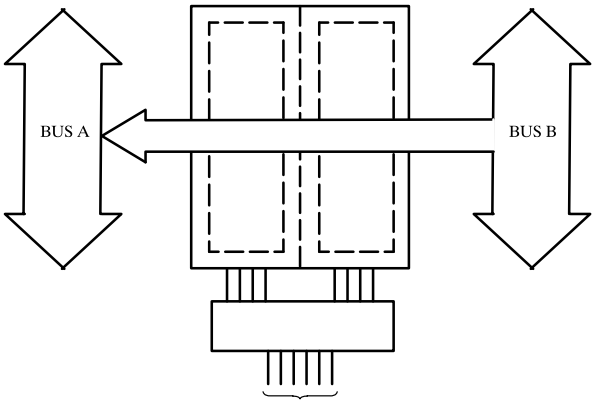
Name	Description
A	Data Register A Inputs Data Register B Outputs
B	Data Register B Inputs Data Register A Outputs
CLKAB, CLKBA	Clock Pulse Inputs
SAB, SBA	Output Data Source Select Inputs
OEAB, $\overline{OEBA}$	Output Enable Inputs

Function Table[1]

Inputs						Data I/O[2]		
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A	B	Operation or Function
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	⌐	⌐	X	X			Store A and B Data
X	H	⌐	H or L	X	X	Input	Unspecified[2]	Store A, Hold B
H	H	⌐	⌐	X[3]	X	Input	Output	Store A in Both Registers
L	X	H or L	⌐	X	X	Unspecified[2]	Input	Hold A, Store B
L	L	⌐	⌐	X	X[3]		Input	Store B in both Registers
L	L	X	X	X	L	Output	Input	Real Time B Data to A Bus
L	L	X	H or L	X	H			Stored B Data to A Bus
H	H	X	X	L	X	Input	Output	Real Time A Data to B Bus
H	H	H or L	X	H	X			Stored A Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Stored A Data to B Bus and
								Stored B Data to A Bus

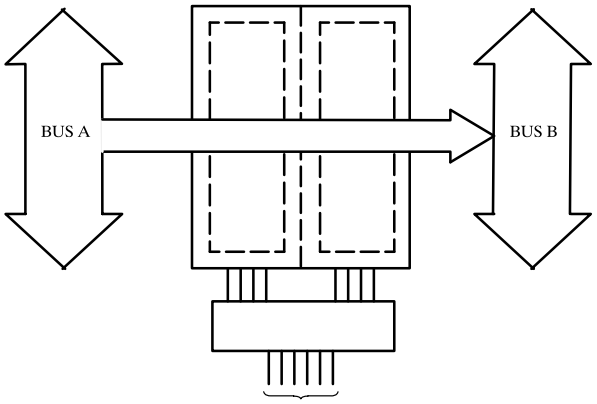
Notes:

1. H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
   ⌐ =LOW-to-HIGH Transition
2. The data output functions may be enabled or disabled by various signals at the OEAB or $\overline{OEBA}$ inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.
3. Select control=L; clocks can occur simultaneously.
   Select control=H; clocks must be staggered to load both registers.



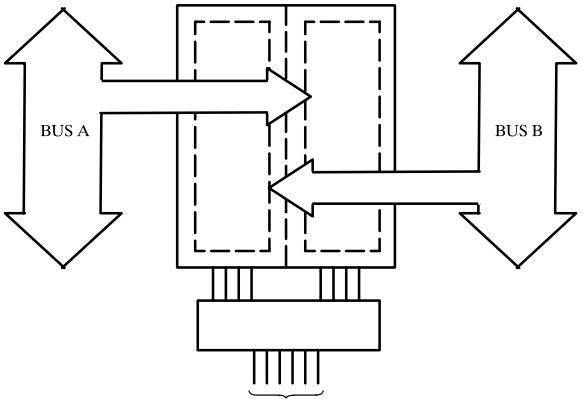
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

Real-Time Transfer
Bus B to Bus A



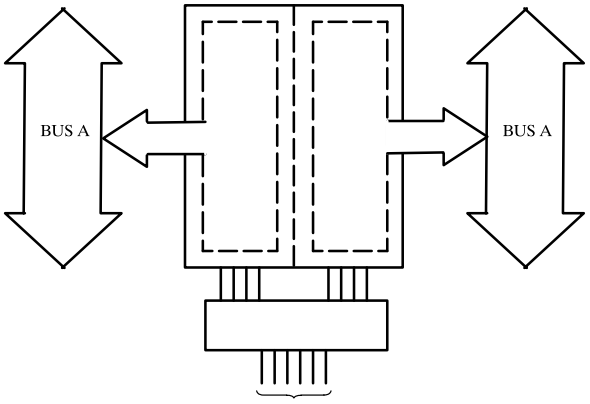
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	X	X	L	X

Real-Time Transfer
Bus A to Bus B



OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
X	H	⌐	X	X	X
L	X	X	⌐	X	X
L	H	⌐	⌐	X	X

Storage from
A and/or B



OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA
H	L	H or L	H or L	H	H

Transfer Stored Data
to A and/or B

Maximum Ratings[4]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... Com'l −55°C to +125°C

Ambient Temperature with
Power Applied ..... Com'l −55°C to +125°C

DC Input Voltage ..... −0.5V to +7.0V

DC Output Voltage ..... −0.5V to +7.0V

DC Output Current
(Maximum Sink Current/Pin) ..... −60 to +120 mA

Power Dissipation 1.0W

Static Discharge Voltage ..... >2001V
(per MIL-STD-883, Method 3015)

Note:

4. Stresses greater than those listed under Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	−40°C to +85°C	5V ± 10%

DC Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions[5]	Min.	Typ.[6]	Max.	Unit
V_{IH}	Input HIGH Voltage	Guaranteed Logic HIGH Level	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Logic LOW Level			0.8	V
V_H	Input Hysteresis			100		mV
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=−18 mA		−0.7	−1.2	V
I_{IH}	Input HIGH Current[7]	V_{CC}=Max., V_I=V_{CC}			±1	µA
I_{IL}	Input LOW Current[7]	V_{CC}=Max., V_I=GND			±1	µA
I_{OZH}	High Impedance Output[7] Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=2.7V			±1	µA
I_{OZL}	High Impedance Output[7] Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=0.5V			±1	µA
I_{OS}	Short Circuit Current	V_{CC}=Max., V_{OUT}=GND[8]	−80	−140	−200	mA
I_O	Output Drive Current	V_{CC}=Max., V_{OUT}=2.5V[8]	−50		−180	mA
I_{OFF}	Power-Off Disable[7]	V_{CC}=0V, V_{OUT}≤4.5V			±1	µA

Output Drive Characteristics for CY74FCT16652T

Parameter	Description	Test Conditions[5]	Min.	Typ.[6]	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=−3 mA	2.5	3.5		V
		V_{CC}=Min., I_{OH}=−15 mA	2.4	3.5		V
		V_{CC}=Min., I_{OH}=−32 mA[9]	2.0	3.0		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=64 mA		0.2	0.55	V

Output Drive Characteristics for CY74FCT162652T

Parameter	Description	Test Conditions[5]	Min.	Typ.[6]	Max.	Unit
I_{ODL}	Output LOW Current	V_{CC}=5V, V_{IN}=V_{IH} or V_{IL}, V_{OUT}=1.5V[8]	60	115	150	mA
I_{ODH}	Output HIGH Current	V_{CC}=5V, V_{IN}=V_{IH} or V_{IL}, V_{OUT}=1.5V[8]	−60	−115	−150	mA
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=−24 mA	2.4	3.3		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=24 mA		0.3	0.55	V

Capacitance (T_A = +25°C, f = 1.0 MHz)

Parameter	Description[10]	Test Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	4.5	6.0	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	5.5	8.0	pF

Notes:

5. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
6. Typical values are at V_{CC}=5.0V, +25°C ambient.
7. The test limit for this parameter is +5mA at T_A=−55°C.
8. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
9. Duration of the condition cannot exceed one second.
10. This parameter is measured at characterization but not tested.

Power Supply Characteristics

Param.	Description	Test Conditions[11]		Min.	Typ.[12]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC}=Max.	$V_{IN} \le 0.2V$ $V_{IN} \ge V_{CC}-0.2V$	—	5	500	µA
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V_{CC} = Max. V_{IN}=3.4V[13]		—	0.5	1.5	mA
I_{CCD}	Dynamic Power Supply Current[14]	V_{CC}=Max. Outputs Open OEAB=$\overline{OEAB}$=GND One Input Toggling 50% Duty Cycle	$V_{IN}=V_{CC}$ or V_{IN}=GND	—	75	120	µA/ MHz
I_C	Total Power Supply Current[15]	V_{CC}=Max. Outputs Open f_0=10 MHz (CLKBA) 50% Duty Cycle OEAB=$\overline{OEBA}$=GND One-Bit Toggling f_1=5 MHz 50% Duty Cycle	$V_{IN}=V_{CC}$ or V_{IN}=GND	—	0.8	1.7	mA
			V_{IN}=3.4V or V_{IN}=GND	—	1.3	3.2	
		V_{CC}=Max. Outputs Open f_0=10 MHz (CLKBA) 50% Duty Cycle OEAB=$\overline{OEBA}$=GND Sixteen Bits Toggling f_1=2.5 MHz 50% Duty Cycle	$V_{IN}=V_{CC}$ or V_{IN}=GND	—	3.8	6.5[16]	
			V_{IN}=3.4V or V_{IN}=GND	—	8.3	20.0[16]	

Notes:

11. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
12. Typical values are at V_{CC}=5.0V +25° ambient.
13. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
14. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
15. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC}+\Delta I_{CC}D_HN_T+I_{CCD}(f_0/2 + f_1N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
16. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

Switching Characteristics Over the Operating Range[17]

Parameter	Description	Cond.[18]	74FCT16652T 74FCT162652T		74FCT16652AT 74FCT162652AT		74FCT16652CT 74FCT162652CT		Unit	Fig. No.[19]
			Min.	Max.	Min.	Max.	Min.	Max.		
t_{PLH} t_{PHL}	Propagation Delay Bus to Bus	C_L=50 pF R_L=500Ω	1.5	9.0	1.5	6.3	1.5	5.4	ns	1, 3
t_{PZH} t_{PHL}	Output Enable Time OEAB or $\overline{OEBA}$ to Bus		1.5	14.0	1.5	9.8	1.5	7.8	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time OEAB or $\overline{OEBA}$ to Bus		1.5	9.0	1.5	6.3	1.5	6.3	ns	1, 7, 8
t_{PLH} t_{PHL}	Propagation Delay Clock to Bus		1.5	9.0	1.5	6.3	1.5	5.7	ns	1, 5
t_{PLH} t_{PHL}	Propagation Delay SBA or SAB to Bus		1.5	11.0	1.5	7.7	1.5	6.2	ns	1, 5
t_{SU}	Set-Up time HIGH or LOW Bus to Clock		2.0	—	2.0	—	2.0	—	ns	4
t_H	Hold Time HIGH or LOW Bus to Clock		1.5	—	1.5	—	1.5	—	ns	4
t_W	Clock Pulse Width HIGH or LOW		5.0	—	5.0	—	5.0	—	ns	5
$t_{SK(O)}$	Output Skew[20]		—	0.5	—	0.5	—	0.5	ns	

Notes:
17. Minimum limits are guaranteed, but not tested, on propagation delays.
18. See test circuits and waveforms.
19. See “Parameter Measurement Information” in the General Information section.
20. Skew between any two outputs of the same package switching in the same direction. This parameter guaranteed by design.

Ordering Information CY74FCT16652

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.4	CY74FCT16652CTPAC	Z56	56-Lead (240-Mil) TSSOP	Commercial
	CY74FCT16652CTPVC	O56	56-Lead (300-Mil) SSOP	
6.3	CY74FCT16652ATPAC	Z56	56-Lead (240-Mil) TSSOP	Commercial
	CY74FCT16652ATPVC	O56	56-Lead (300-Mil) SSOP	
9.0	CY74FCT16652TPAC	Z56	56-Lead (240-Mil) TSSOP	Commercial
	CY74FCT16652TPVC	O56	56-Lead (300-Mil) SSOP	

Ordering Information CY74FCT162652

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
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	CY74FCT162652CTPVC	O56	56-Lead (300-Mil) SSOP	
6.3	CY74FCT162652ATPAC	Z56	56-Lead (240-Mil) TSSOP	Commercial
	CY74FCT162652ATPVC	O56	56-Lead (300-Mil) SSOP	
9.0	CY74FCT162652TPAC	Z56	56-Lead (240-Mil) TSSOP	Commercial
	CY74FCT162652TPVC	O56	56-Lead (300-Mil) SSOP	

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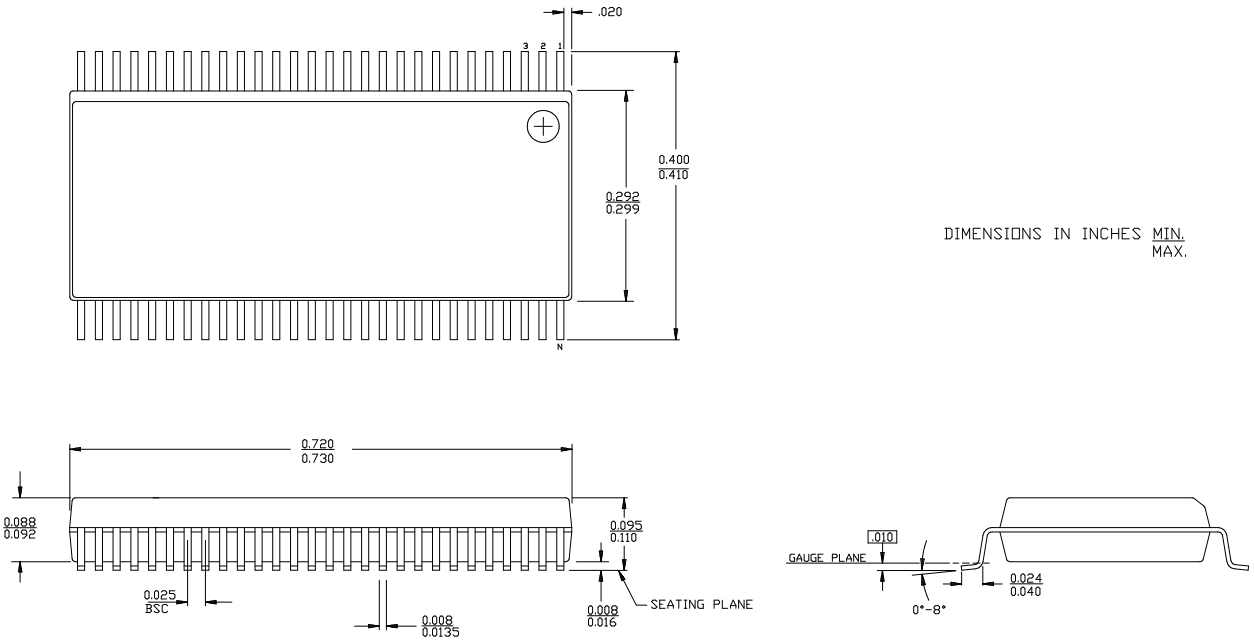
Package Diagrams

56-Lead Shrunk Small Outline Package O56



56-Lead Thin Shrunk Small Outline Package Z56